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IXDN0018

October 16, 2003

MOSFET and IGBT die and 150 mm wafer products

Customer: Various

IXYS product type: MOSFET and IGBT die and 150 mm wafer products.

Description of changes:

1. Wafer and die thickness reduction from 420 um to 300 um.
2. Backside solderable metal change from silver to gold.

Reasons for change:

Improvement of thermal properties of the product (lower Rth).
 Elimination of backside oxidation risks during the storage of the die and wafer products.

Identification: Shiny gold backside of dice and wafers versus dull silver backside

Schedule of change: March-December 2003

Influence on quality: None

Internal reference document: CR0016

Questions to be addressed to: Vladimir Tsukanov, Director of Engineering;
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Customer response:

Company: _____

Name and Position: _____

Phone/Fax/e-mail: _____

CHANGES ARE:

___ ACCEPTED

___ NOT ACCEPTED (please comment)

___ TO BE EVALUATED/ MORE INFORMATION IS NEEDED (please comment)

COMMENTS: _____

WRITTEN RESPONSE MUST BE RECEIVED WITHIN 30 DAYS OF THE DATE OF THIS PCN.
 OTHERWISE IXYS WILL CONSIDER CHANGE APPROVED.
 PLEASE CONTACT FACTORY REGARDING AVAILABILITY OF OLD TYPE PRODUCTS.